

Listing of Claims:

1-4. (Canceled)

5. (Previously presented) A process for producing a copper clad laminate comprising,

providing an insulation layer constituent material having a first and a second side,

coating said first side with a first copper foil of a first thickness,

coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,

hot pressing said assembly to produce said laminate,

wherein said first copper foil is not recrystallized during said hot pressing, and

wherein said second copper foil is recrystallized during said hot pressing.

6. (Previously presented) The process of claim 5, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

7. (Previously presented) The process of claim 5, wherein said insulation layer constituent material is a resin.

8. (Previously presented) The process of claim 5, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.

9. (Previously presented) The process of claim 5, wherein said second copper foil is a S-HTE foil.

10. (Previously presented) The process of claim 5, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

11. (Previously presented) A process for producing a copper clad laminate comprising,
 providing an insulation layer constituent material having a first and a second side,
 coating said first side with a first copper foil of a first thickness,
 coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,
 hot pressing said assembly to produce said laminate,
 wherein said first and second copper foils are recrystallized during said hot pressing, wherein said second copper foil is more recrystallized than said first copper foil.

12. (Previously presented) The process of claim 11, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

13. (Previously presented) The process of claim 11, wherein said insulation layer constituent material is a resin.

14. (Previously presented) The process of claim 11, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.

15. (Previously presented) The process of claim 11, wherein said second copper foil is a S-HTE foil.

16. (Previously presented) The process of claim 11, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

17. (Previously presented) A process for producing a copper clad laminate, providing an insulation layer constituent material having a first and a second side,
coating said first side with a first copper foil of a first thickness,
coating said second side with a second copper foil of a second thickness to produce an insulation layer constituent material, first copper foil and second copper foil assembly, wherein the thickness of said second foil is greater than the thickness of said first foil,
hot pressing said assembly to produce said laminate,
wherein said first and second copper foil contract during said hot pressing,
wherein said second copper foil contracts to a larger extent than said first copper foil during said hot pressing.

18. (Previously presented) The process of claim 17, wherein the thickness of the second foil is four times or less than the thickness of the first foil.

19. (Previously presented) The process of claim 17, wherein said insulation layer constituent material is a resin.

20. (Previously presented) The process of claim 17, wherein said second copper foil contracts about 0.05% under pressing conditions of 180°C and 1hr.

21. (Previously presented) The process of claim 17, wherein said second copper foil is a S-HTE foil.

22. (Previously presented) The process of claim 17, wherein, after hot pressing, the Young's modulus of said first copper foil is 1.1 times more than the Young's modulus of said second copper foil.

23-29. (Canceled)

30. (New) A method of reducing warping of a copper clad laminate during production thereof, said method comprising the steps of:

- coating a first side of an insulation layer with a first copper foil,
- coating a second side of said insulation layer with a second copper foil,
- wherein said second copper foil is thicker than said first copper foil, and
- said second copper foil is more recrystallizable than said first copper foil at a pressing temperature, and
- hot pressing said first and second copper foils to said insulation layer at said pressing temperature,
- thereby reducing warping of said copper clad laminate during production thereof.